Docket No.

221014US90PCT

TES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Yasuii HIRAMATSU, et al.

SERIAL NO:

10/070,443

GAU:

FILED:

FOR:

June 24, 2002

EXAMINER: FUQUA, SHAWNTINA T

SEMICONDUCTOR MANUFACTURING/TESTING CERAMIC HEATER, PRODUCTION METHOD FOR THE CERAMIC HEATER AND PRODUCTION SYSTEM FOR THE CERAMIC HEATER

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

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SIR:

Applicant(s) wish to disclose the following information.

MAR 1 1 2004

TECHNOLOGY CENTER R3700

REFERENCES

☐ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.

☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the application(s) is attached along with PTO 1449.

A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.

□ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Masayasu Mori

Registration No. 47,301

Joseph A. Scafetta, Jr. Registration No. 26, 803

03/08/2004 SSANDARA 00000021 10070443

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Customer Number

Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 05/03)

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Vasuiji HIRAMATSU, et al. Filing DATE June 24, 2002 3742	(Modified)	ified) PATENT AND TRADEMARK OFFICE		221014US90PCT		10/070,443			
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June 24, 2002 3742	LIST OF REFERENCES CITED BY APPLICANT			Yasuji HIRAMATSU, et al.					
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^{*}Present Application; listed for information *Abandoned Application

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